



Integrated Device Technology, Inc.
 6024 Silver Creek Valley Road
 San Jose, CA 96138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: A0709-02 (R1) Product Affected: 10mm x 10mm VFQFP-N-72 (green package) Date Effective: March 21, 2008	DATE January 21, 2008	MEANS OF DISTINGUISHING CHANGED DEVICES: <input type="checkbox"/> Product Mark <input checked="" type="checkbox"/> Back Mark Lot # will have a "Y" suffix <input type="checkbox"/> Date Code <input type="checkbox"/> Other
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Contact: Bimla Paul Title: Product Quality Assurance Phone #: (408) 574-6419 Fax #: (408) 284-8362 E-mail: Bimla.Paul@idt.com	Attachment: <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No Samples: Contact your local samples representative for sample requests. Samples are presently available for selective products
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DESCRIPTION AND PURPOSE OF CHANGE:

<input type="checkbox"/> Die Technology <input type="checkbox"/> Wafer Fabrication Process <input type="checkbox"/> Assembly Process <input type="checkbox"/> Equipment <input checked="" type="checkbox"/> Material <input type="checkbox"/> Testing <input type="checkbox"/> Manufacturing Site <input type="checkbox"/> Data Sheet <input type="checkbox"/> Other	<p>This notification is to notify our customers that IDT has successfully completed the evaluation of Copper bond wire for 10mm x 10mm VFQFP-N-72 (green package) and plans to ship product with copper bond wire process in March 2008. Please refer to following attachments for additional information:</p> <p>Attachment 1 - Qualification Data Attachment 2 - Affected Part# List</p>
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RELIABILITY/QUALIFICATION SUMMARY:
 There is no expected change to the product quality or reliability performance.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____	<input type="checkbox"/> <i>Approval for shipments prior to effective date.</i>
Name/Date: _____	E-Mail Address: _____
Title: _____	Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____



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ATTACHMENT 1 - PCN # : A0709-02(R1)

PCN Type: Assembly Material Change - Gold wire to Copper wire

Data Sheet Change: None

There is no change in product MSL level as a result of this material change.

Detail Of Change:

This notification is to notify our customers that IDT has successfully completed the evaluation of Copper bond wire for 10mm x 10mm VFQFP-N-72 (green package) and plans to ship product with copper bond wire process in March 2008.

Copper bond wire process is presently used by semiconductor suppliers due to the following key advantages:

- A. Better electrical performance - higher current handling capability, ~18% improvement in resistance for 1 mil bond wire.
- B. Better high temperature bake performance. Minimal intermetallic compound formation. Please refer to Figure 1 for more details
- C. Stiffer wire – Minimize wire swaying, longer wires than gold is now possible.

Please refer to following attachments for additional information:

- Attachment 1 - Qualification Data
- Attachment 2 - Affected Part# List

Customers may expect to receive shipments no sooner than 60 days from the date of this notification, January 21, 2008.

We request you acknowledge receipt of this notification with in **30 days** of the date of this PCN notification.

If you require samples to conduct an evaluation, please make your sample request within **15 days** as samples are not built ahead of the change for all device options. You may contact your local sales representative to acknowledge this PCN and request samples.



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ATTACHMENT 1 - PCN # : A0709-02 (R1)

Package Family	Samples Availability	Qualification Status	Production Shipments
VFQFP-N-72	Now	Completed	March' 08

Assembly Material: There is no change in the mold compound and die attach material. The material set used in assembly is in compliance with RoHS 6 requirements.

Sample Availability: Samples are not built ahead of the change for all device types and may not be available for all affected device types.
 Please contact your local IDT sales representative for your sample request and availability.

Qualification Test Plan and Test Results:

The following tests were successfully completed.

Test Description and Qualification Data

Test Description	Test Method	Test Results	
		Lot 1	Lot 2
		SS / Rej	SS / Rej
* High Accelerated Stress Test (Biased, 130 °C/85% RH, 100 Hrs)	JESD22-A110-B	45/0	45/0
* Temperature Cycle / Condition B (-55 °C to +125 °C, 1000 Cyc)	JESD22-A104-B	45/0	45/0
High Temp. Storage (150 °C, 1000 Hrs)	JESD22-A103-B	77/0	77/0
Ball Shear Test	JESD22-B116	5/0	5/0
Bond Pull Test	MIL-STD-883, M 2011	5/0	5/0
X-ray Examination	IDT Spec MAC3012	45/0	45/0

Note: * Test requires moisture pre-conditioning sequence per JESD22-A113C.

Product Electrical Characterization:

Product electrical characterization has been successfully completed on representative product families and copper wire performance was comparable to gold wire performance.



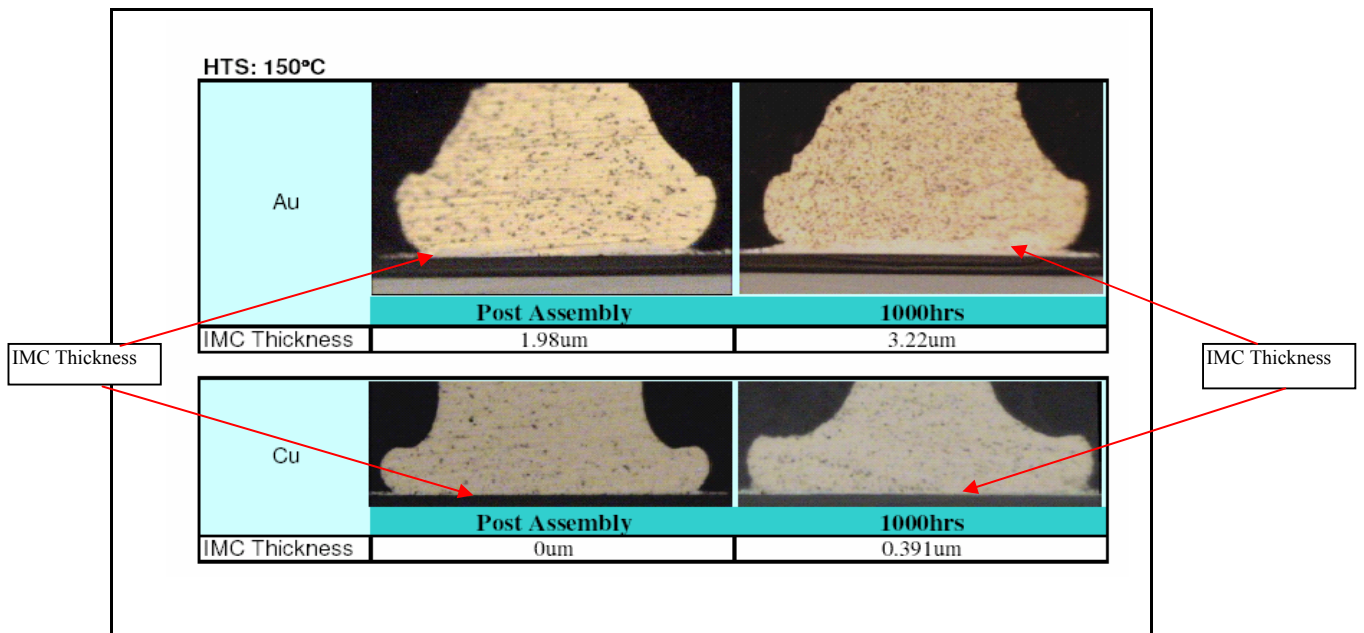
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Figure 1

Intermetallic Compound Growth Comparison (Au Bond Wire Vs. Cu Bond Wire)



Conclusion:

Better high temperature bake performance. Minimal intermetallic compound formation with Cu bond wire



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ATTACHMENT 2 - PCN #: A0709-02 (R1)

Affected Part Number List

Part Number	Part Number	Part Number
9LPRS114AKLF	ICS9LPRS395BKLF	ICS9LPRS914EKLF
9LPRS118AKLF	ICS9LPRS397AKLF	ICS9LPRS915AKLF
9LPRS391CKLF	ICS9LPRS397BKLF	ICS9LPRS918AKLF
9LPRS395CKLF	ICS9LPRS398AKLF	ICS9LPRS918BKLF
9LPRS398CKLF	ICS9LPRS398BKLF	ICS9LPRS918CKLF
9LPRS476DKLF	ICS9LPRS470BKLF	ICS9LPRS918DKLF
9LPRS478CKLF	ICS9LPRS470CKLF	ICS9LPRS918EKLF
9LPRS918JKLF	ICS9LPRS476AKLF	ICS9LPRS918HKLF
9LPRS919JKLF	ICS9LPRS476BKLF	ICS9LPRS919AKLF
9LPRS929AKLF	ICS9LPRS476CKLF	ICS9LPRS919BKLF
CLK503J45KLF	ICS9LPRS478AKLF	ICS9LPRS919CKLF
ICS9LPR325CKLF	ICS9LPRS478BKLF	ICS9LPRS919DKLF
ICS9LPR332AKLF	ICS9LPRS488AKLF	ICS9LPRS919EKLF
ICS9LPRS325CKLF	ICS9LPRS488BKLF	ICS9LPRS919HKLF
ICS9LPRS325DKLF	ICS9LPRS911AKLF	ICS9LPRS924AKLF
ICS9LPRS387AKLF	ICS9LPRS911BKLF	ICS9LPRS928AKLF
ICS9LPRS392AKLF	ICS9LPRS914CKLF	ICS9LPRS929AKLF
ICS9LPRS395AKLF	ICS9LPRS914DKLF	

Note: For T & R (shipping method) "T" is added to ICS and "8" is added to IDT P/N